

# 6SP0110T2Bx-FS400R07A1E3

## Target Data Sheet

Compact, high-performance, plug-and-play six-channel IGBT driver based on SCALE-2 technology for automotive modules HybridPACK™ 1

### Abstract

The SCALE-2 plug-and-play driver 6SP0110T2Bx-FS400R07A1E3 is a compact six-channel intelligent gate driver designed for Infineon's HybridPACK™ 1 IGBTs FS400R07A1E3. The driver features an electrical interface with a built-in DC/DC power supply.

For drivers adapted to other types of high-power and high-voltage IGBT modules, refer to

[www.IGBT-Driver.com/go/plug-and-play](http://www.IGBT-Driver.com/go/plug-and-play)

### Features

- ✓ Plug-and-play solution
- ✓ Shortens application development time
- ✓ Extremely reliable; long service life
- ✓ Built-in DC/DC power supply
- ✓ 24-pin connector
- ✓ Duty cycle 0... 100%
- ✓ Active clamping of  $V_{ce}$  at turn-off
- ✓ IGBT short-circuit protection
- ✓ Short-pulse suppression
- ✓ Monitoring of supply voltage
- ✓ Safe isolation to IEC 60664-1 and EN 50178
- ✓ UL compliant
- ✓ Suitable for FS400R07A1E3

### Applications

- ✓ Automotive

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### Safety Notice!

The data contained in this data sheet is intended exclusively for technically trained staff. Handling all high-voltage equipment involves risk to life. Strict compliance with the respective safety regulations is mandatory!

Any handling of electronic devices is subject to the general specifications for protecting electrostatic-sensitive devices according to international standard IEC 60747-1, Chapter IX or European standard EN 100015 (i.e. the workplace, tools, etc. must comply with these standards). Otherwise, this product may be damaged.

### Important Product Documentation

This data sheet contains only product-specific data. For a detailed description, must-read application notes and common data that apply to the whole series, please refer to "Description & Application Manual for 6SP0110T SCALE-2 IGBT Drivers" on [www.IGBT-Driver.com/go/6SP0110T](http://www.IGBT-Driver.com/go/6SP0110T).

When applying SCALE-2 plug-and-play drivers, please note that these drivers are specifically adapted to a particular type of IGBT module. Therefore, the type designation of SCALE-2 plug-and-play drivers also includes the type designation of the corresponding IGBT module. These drivers are not valid for IGBT modules other than those specified. Incorrect use may result in failure.

### Mechanical Dimensions

Dimensions: See "Description & Application Manual for 6SP0110T SCALE-2 IGBT Drivers"

Mounting principle: Soldered and connected with screws to HybridPACK™ 1 module FS400R07A1E3

### Absolute Maximum Ratings

Parameter	Remarks	Min	Max	Unit
Supply voltage $V_{CC}$	VCC to GND	0	16	V
Logic input and output voltages	To GND	-0.5	VCC+0.5	V
SO <sub>x</sub> current	Fault condition, total current		20	mA
Gate peak current $I_{out}$	Note 1	-8	+8	A
Average supply current $I_{CC}$	Note 2		t.b.d.	mA
Output power per gate	Ambient temperature <70°C (Note 3)		t.b.d.	W
	Ambient temperature 85°C (Note 3)		t.b.d.	W
Switching frequency F			10	kHz
Test voltage (50Hz/1min.)	Primary to secondary (Note 16)		2900	$V_{AC(eff)}$
	Secondary to secondary (Note 16)		1450	$V_{AC(eff)}$
DC-link voltage	Note 4		450	V
dV/dt	Rate of change of input to output voltage (Note 5)		t.b.d.	kV/μs
Operating voltage	Primary/secondary, secondary/secondary		650	$V_{peak}$
Operating temperature		-40	+85	°C
Storage temperature		-40	+90	°C

### Recommended Operating Conditions

Parameter	Remarks	Min	Typ	Max	Unit
Supply voltage $V_{CC}$	To GND	14.5	15	15.5	V
Resistance from TB to GND	Blocking time $\neq$ 0, ext. value	t.b.d.		$\infty$	k $\Omega$
SO <sub>x</sub> current	Fault condition, 5V logic			5	mA

### Electrical Characteristics

All data refer to +25°C and  $V_{CC} = 15V$  unless otherwise specified

Power Supply	Remarks	Min	Typ	Max	Unit
Supply current $I_{CC}$	Without load		100		mA
Efficiency $\eta$	Internal DC/DC converter		85		%
Coupling capacitance $C_{io}$	Primary side to secondary side, total, per channel		t.b.d.		pF

Power Supply Monitoring	Remarks	Min	Typ	Max	Unit
Supply threshold $V_{CC}$	Primary side, clear fault	11.9	12.6	13.3	V
	Primary side, set fault (Note 6)	11.3	12.0	12.7	V
Monitoring hysteresis	Primary side, set/clear fault	0.35			V
Supply threshold $V_{isoX}-V_{eex}$	Secondary side, clear fault	12.1	12.6	13.1	V
	Secondary side, set fault (Note 7)	11.5	12.0	12.5	V
Monitoring hysteresis	Secondary side, set/clear fault	0.35			V
Supply threshold $V_{eex}-V_{COMx}$	Secondary side, clear fault	5	5.15	5.3	V
	Secondary side, set fault (Note 7)	4.7	4.85	5	V
Monitoring hysteresis	Secondary side, set/clear fault	0.15			V

Logic Inputs and Outputs	Remarks	Min	Typ	Max	Unit
Input impedance	Note 8		4.7		k $\Omega$
Turn-on threshold	V(INx) (Note 9)		8.8		V
Turn-off threshold	V(INx) (Note 9)		5.8		V
SO <sub>x</sub> output voltage	Fault condition, $I(SO_x) < 8mA$			0.7	V

Short-circuit Protection	Remarks	Min	Typ	Max	Unit
Vce-monitoring threshold	Between auxiliary terminals		10.2		V
Response time	DC-link voltage = 450V (Note 10)		3.6		$\mu$ s
Blocking time	After fault (Note 11)		90		ms

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Timing Characteristics	Remarks	Min	Typ	Max	Unit
Turn-on delay $t_{d(on)}$	Note 12		t.b.d.		ns
Turn-off delay $t_{d(off)}$	Note 12		t.b.d.		ns
Jitter of turn-on delay	Note 18		t.b.d.		ns
Jitter of turn-off delay	Note 18		t.b.d.		ns
Output rise time $t_{r(out)}$	$G_x$ to $E_x$ (Note 13)		t.b.d.		ns
Output fall time $t_{f(out)}$	$G_x$ to $E_x$ (Note 13)		t.b.d.		ns
Dead time between outputs	Half-bridge mode		1.7		$\mu$ s
Jitter of dead time	Half-bridge mode		t.b.d.		ns
Short-pulse suppression	Turn-on input signal		520		ns
	Turn-off input signal		670		ns
Transmission delay of fault state	Note 14		450		ns
Outputs	Remarks	Min	Typ	Max	Unit
Turn-on gate resistor $R_{g(on)}$	Note 15		3.0		$\Omega$
Turn-off gate resistor $R_{g(off)}$	Note 15		7.5		$\Omega$
Gate voltage at turn-on			15		V
Gate-voltage at turn-off	$P = 0W$		-8.8		V
	$P = 1W$		-7.4		V
Gate resistance to COMx			4.7		k $\Omega$
Electrical Isolation	Remarks	Min	Typ	Max	Unit
Test voltage (50Hz/1s)	Primary to secondary side (Note 16)	2900	2950	3000	$V_{eff}$
	Secondary to secondary side (Note 16)	1450	1475	1500	$V_{eff}$
Partial discharge extinction volt.	Primary to secondary side (Note 17)	813			$V_{peak}$
	Secondary to secondary side (Note 17)	650			$V_{peak}$
Creepage distance	Primary to secondary side	4.6			mm
	Secondary to secondary side	2.3			mm
	Secondary to NTC (Note 19)	4.6			mm
Clearance distance	Primary to secondary side	4.6			mm
	Secondary to secondary side	2.3			mm
	Secondary to NTC (Note 19)	4.6			mm

### Footnotes to the Key Data

- 1) The gate current is limited by the gate resistors located on the driver.
- 2) If the specified value is exceeded, this indicates a driver overload. It should be noted that the driver is not protected against overload.
- 3) If the specified value is exceeded, this indicates a driver overload. It should be noted that the driver is not protected against overload. From 70°C to 85°C, the maximum permissible output power can be linearly interpolated from the given data.

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- 4) This limit is due to active clamping. Refer to the "Description & Application Manual for 6SP0110T SCALE-2 IGBT Drivers". At ambient temperatures below 0°C and DC-link voltages higher than 430V a secondary undervoltage fault may be generated. The safe operating limits are defined at -40°C/430V and 0°C/450V. Between 0°C and -40°C the DC-link voltage can be linearly interpolated from the given data. It is therefore not recommended to operate the driver outside the given limits.
- 5) This specification guarantees that the drive information will be transferred reliably even at a high DC-link voltage and with ultra-fast switching operations.
- 6) Undervoltage monitoring of the primary-side supply voltage (VCC to GND). If the voltage drops below this limit, a fault is transmitted to the corresponding outputs and the IGBTs are switched off.
- 7) Undervoltage monitoring of the secondary-side supply voltage (Visox to Veex and Veex to COMx which correspond with the approximate turn-on and turn-off gate-emitter voltages). If the corresponding voltage drops below this limit, the IGBT is switched off and a fault is transmitted to the corresponding output.
- 8) The input impedance can be modified (customer-specific solution).
- 9) Turn-on and turn-off threshold values can be increased (customer-specific solution).
- 10) Resulting pulse width of the direct output of the gate drive unit for short-circuit type I (excluding the delay of the gate resistors).
- 11) Factory set value. The blocking time can be reduced with an external resistor. Refer to the "Description & Application Manual for 6SP0110T SCALE-2 IGBT Drivers".
- 12) Measured from the transition of the turn-on or turn-off command at the driver input to direct output of the gate drive unit (excluding the delay of the gate resistors).
- 13) Output rise and fall times are measured between 10% and 90% of the nominal output swing with an output load of 10Ω and 40nF. The values are given for the driver side of the gate resistors. The time constant of the output load in conjunction with the present gate resistors leads to an additional delay at the load side of the gate resistors.
- 14) Transmission delay of the fault state from the secondary side to the primary status outputs.
- 15) The gate resistors can be leaded or surface mounted. CONCEPT reserves the right to determine which type will be used. Typically, higher quantities will be produced with SMD resistors and small quantities with leaded resistors.
- 16) HiPot testing (= dielectric testing) must generally be restricted to suitable components. This gate driver is suited for HiPot testing. Nevertheless, it is strongly recommended to limit the testing time to 1s slots as stipulated by EN 50178. Excessive HiPot testing at voltages much higher than 2900V<sub>AC(eff)</sub> may lead to insulation degradation. No degradation has been observed over 1min. testing at 2900V<sub>AC(eff)</sub>. Every production sample shipped to customers has undergone 100% testing at the given value or higher (<5100V<sub>eff</sub>) for 1s.
- 17) Partial discharge measurement is performed in accordance with IEC 60270 and isolation coordination specified in EN 50178. The partial discharge extinction voltage between primary and either secondary side of a phase is coordinated for safe isolation to EN 50178.
- 18) Jitter measurements are performed with input signals INx\_x switching between 0V and 15V referred to GND, with a corresponding rise time and fall time of 8ns.
- 19) Every NTC thermistor output of the IGBT module is protected with a 24V transient voltage suppressor diode and a series resistor of 20Ω.

### Legal Disclaimer

This data sheet specifies devices but cannot promise to deliver any specific characteristics. No warranty or guarantee is given – either expressly or implicitly – regarding delivery, performance or suitability.

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**Ordering Information**

The general terms and conditions of delivery of CT-Concept Technologie AG apply.

**CONCEPT Driver Type #****Related IGBT**

6SP0110T2B0-FS400R07A1E3

FS400R07A1E3

Product home page: [www.IGBT-Driver.com/go/6SP0110T](http://www.IGBT-Driver.com/go/6SP0110T)

Refer to [www.IGBT-Driver.com/go/nomenclature](http://www.IGBT-Driver.com/go/nomenclature) for information on driver nomenclature

**Information about Other Products****For other drivers, evaluation systems product documentation and application support**

Please click: [www.IGBT-Driver.com](http://www.IGBT-Driver.com)

**Manufacturer**

CT-Concept Technologie AG  
Intelligent Power Electronics  
Renferstrasse 15  
CH-2504 Biel-Bienne  
Switzerland

Tel. +41 - 32 - 344 47 47

Fax +41 - 32 - 344 47 40

E-mail [Info@IGBT-Driver.com](mailto:Info@IGBT-Driver.com)

Internet [www.IGBT-Driver.com](http://www.IGBT-Driver.com)

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Version from 2011-11-03